



PD57045-E PD57045S-E

RF POWER transistor, LDMOST plastic family N-Channel enhancement-mode lateral MOSFETs

General features

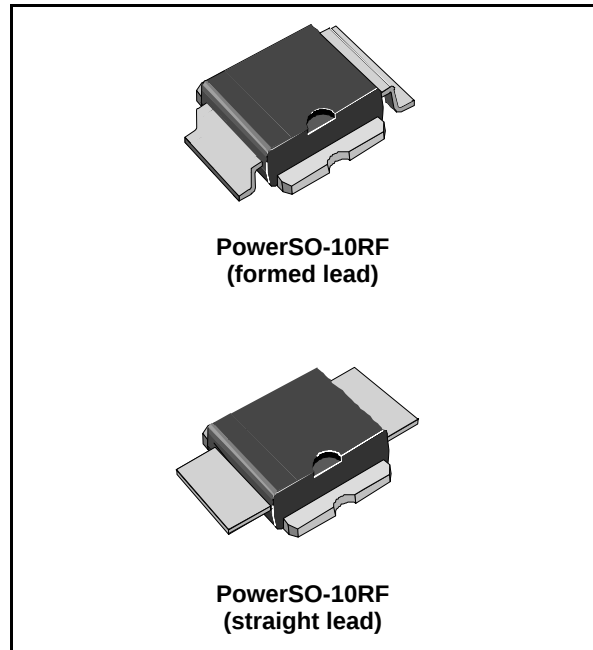
- Excellent thermal stability
- Common source configuration
- $P_{OUT} = 45W$ with 13dB gain @ 945MHz / 28V
- New RF plastic package

Description

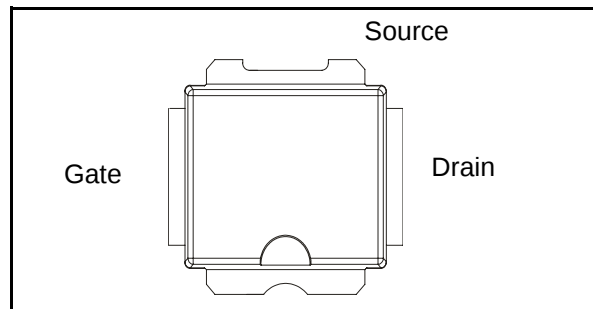
The PD57045 is a common source N-Channel, enhancement-mode lateral Field-Effect RF power transistor. It is designed for high gain, broad band commercial and industrial applications. It operates at 28 V in common source mode at frequencies of up to 1 GHz. PD57045 boasts the excellent gain, linearity and reliability of ST's latest LDMOS technology mounted in the first true SMD plastic RF power package, PowerSO-10RF. PD57045's superior linearity performance makes it an ideal solution for base station applications.

The PowerSO-10 plastic package, designed to offer high reliability, is the first ST JEDEC approved, high power SMD package. It has been specially optimized for RF needs and offers excellent RF performances and ease of assembly.

Mounting recommendations are available in www.st.com/rf/ (look for application note AN1294)



Pin connection



Order codes

Part number	Package	Packing
PD57045-E	PowerSO-10RF (formed lead)	Tube
PD57045S-E	PowerSO-10RF (straight lead)	Tube
PD57045TR-E	PowerSO-10RF (formed lead)	Tape and reel
PD57045STR-E	PowerSO-10RF (straight lead)	Tape and reel

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1 Electrical data

1.1 Maximum ratings

Table 1. Absolute maximum ratings ($T_{CASE} = 25^{\circ}C$)

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-Source Voltage	65	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current	5	A
P_{DISS}	Power Dissipation (@ $T_c = 70^{\circ}C$)	73	W
T_J	Max. Operating Junction Temperature	165	$^{\circ}C$
T_{STG}	Storage Temperature	-65 to +150	$^{\circ}C$

1.2 Thermal data

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Junction - case thermal resistance	1.2	$^{\circ}C/W$

2 Electrical characteristics

$$T_{\text{CASE}} = +25\text{ }^{\circ}\text{C}$$

2.1 Static

Table 3. Static

Symbol	Test conditions		Min	Typ	Max	Unit
$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}$	$I_{\text{DS}} = 1\text{mA}$	65			V
I_{DSS}	$V_{\text{GS}} = 0\text{V}$	$V_{\text{DS}} = 28\text{V}$			1	μA
I_{GSS}	$V_{\text{GS}} = 20\text{V}$	$V_{\text{DS}} = 0\text{V}$			1	μA
$V_{\text{GS(Q)}}$	$V_{\text{DS}} = 28\text{V}$	$I_{\text{D}} = 250\text{mA}$	2.0		5.0	V
$V_{\text{DS(ON)}}$	$V_{\text{GS}} = 10\text{V}$	$I_{\text{D}} = 3\text{A}$		0.7	0.9	V
g_{FS}	$V_{\text{DS}} = 10\text{V}$	$I_{\text{D}} = 4\text{A}$	2.0	2.7		mho
C_{ISS}	$V_{\text{GS}} = 0\text{V}$	$V_{\text{DS}} = 28\text{V}$		86		pF
C_{OSS}	$V_{\text{GS}} = 0\text{V}$	$V_{\text{DS}} = 28\text{V}$		47		pF
C_{RSS}	$V_{\text{GS}} = 0\text{V}$	$V_{\text{DS}} = 28\text{V}$		3.6		pF

2.2 Dynamic

Table 4. Dynamic

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
$P_{1\text{dB}}$	$V_{\text{DD}} = 28\text{V}$ $I_{\text{DQ}} = 250\text{mA}$ $f = 945\text{MHz}$	45			W
G_{P}	$V_{\text{DD}} = 28\text{V}$ $I_{\text{DQ}} = 250\text{mA}$ $P_{\text{OUT}} = 45\text{W}$ $f = 945\text{MHz}$	13	14.5		dB
η_{D}	$V_{\text{DD}} = 28\text{V}$ $I_{\text{DQ}} = 250\text{mA}$ $P_{\text{OUT}} = 45\text{W}$ $f = 945\text{MHz}$	50			%
Load mismatch	$V_{\text{DD}} = 28\text{V}$ $I_{\text{DQ}} = 250\text{mA}$ $P_{\text{OUT}} = 45\text{W}$ $f = 945\text{MHz}$ All phase angles	10:1			VSWR

3 Impedance

Figure 1. Current conventions

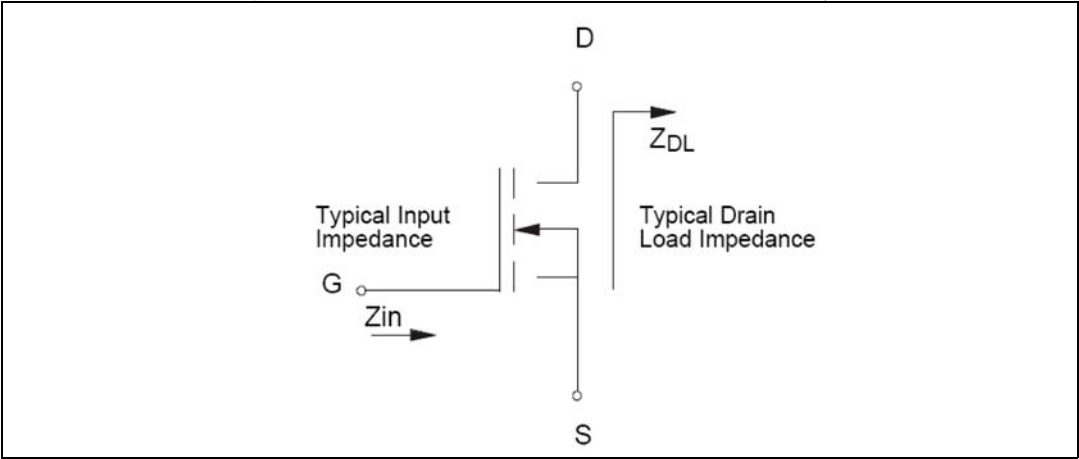


Table 5. Impedance data

Freq. (MHz)	$Z_{IN} (\Omega)$	$Z_{DL}(\Omega)$
925	$.71 + j\ 2.32$	$1.29 - j\ .35$
945	$.69 + j\ 2.92$	$1.25 - j\ .29$
960	$.55 + j\ 2.78$	$1.18 - j\ .83$

4 Typical performance

Figure 2. Capacitance vs drain voltage

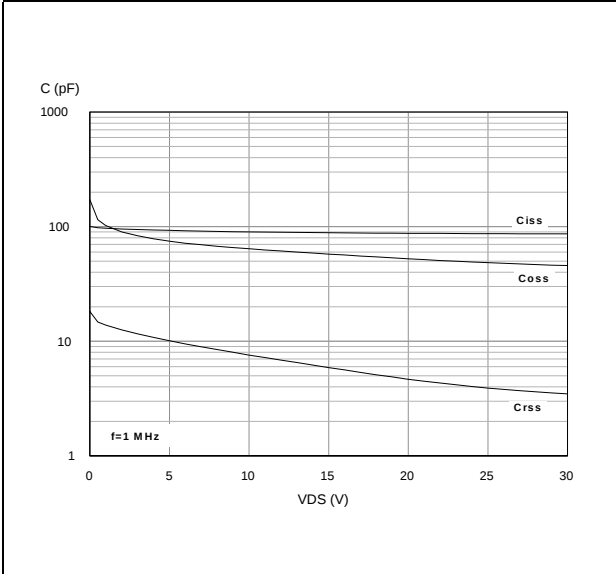


Figure 3. Drain current vs gate voltage

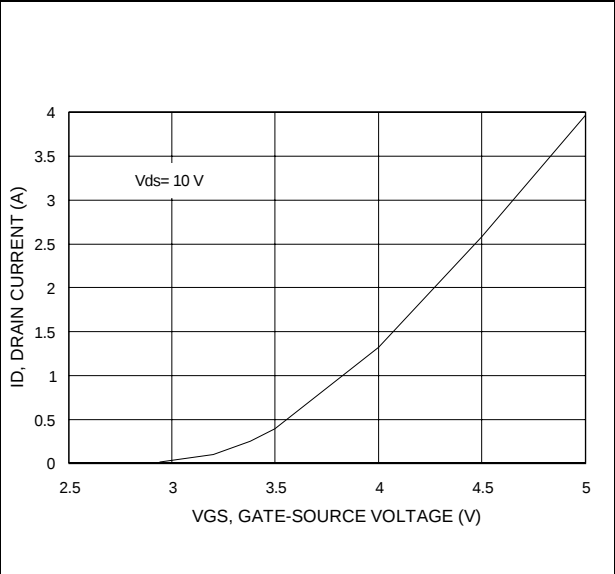


Figure 4. Gate-source voltage vs case temperature

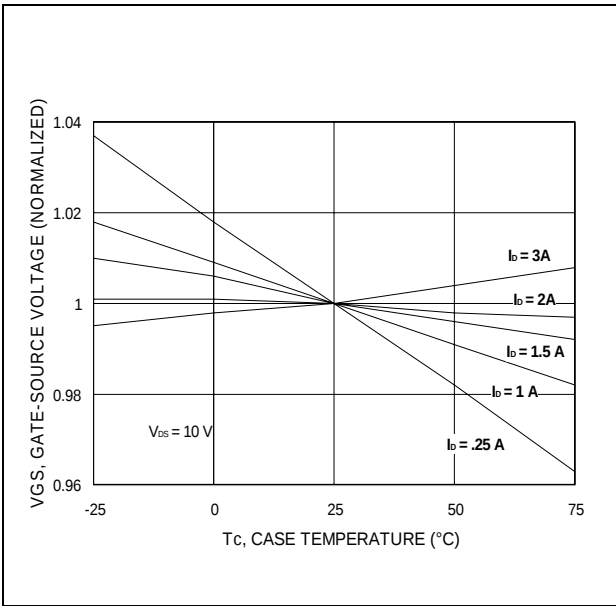
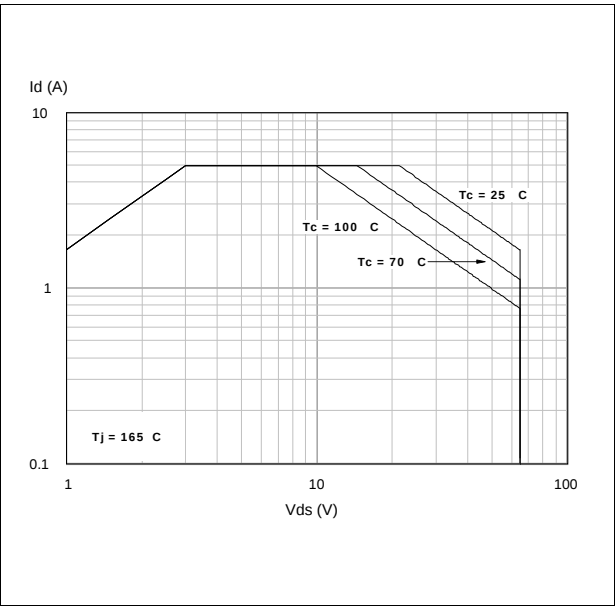


Figure 5. Safe operating area



PD57045S

Figure 6. Output power vs input power

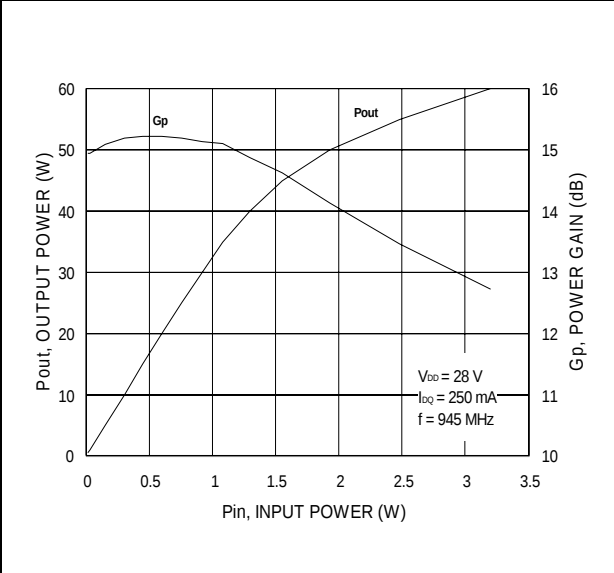


Figure 7. Input return loss vs output power

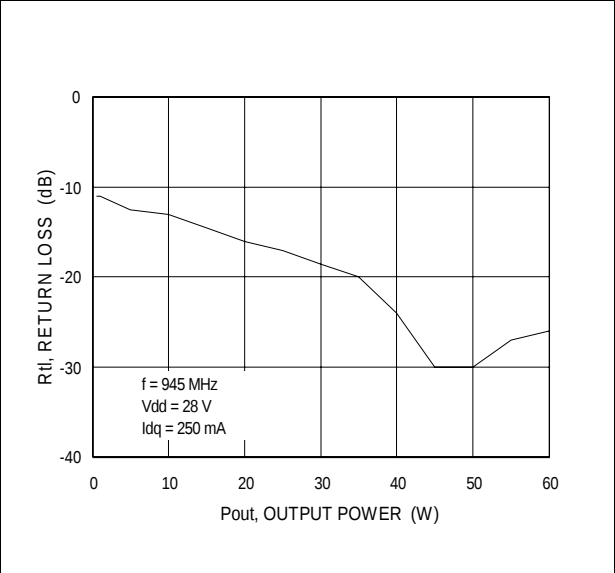


Figure 8. Power gain vs output power

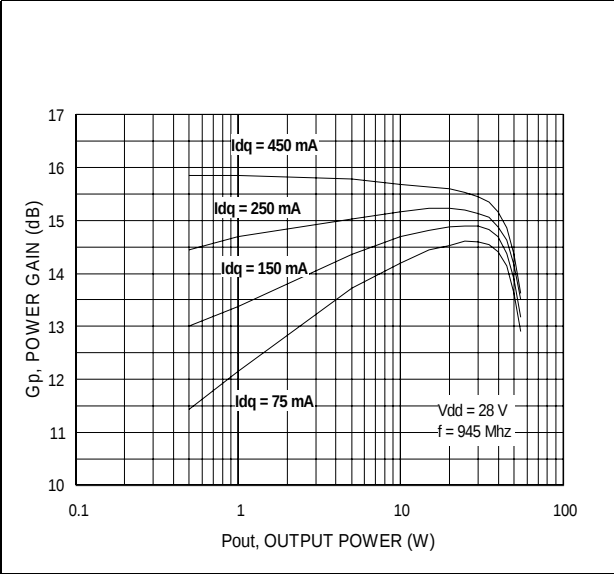


Figure 9. Drain efficiency vs output power

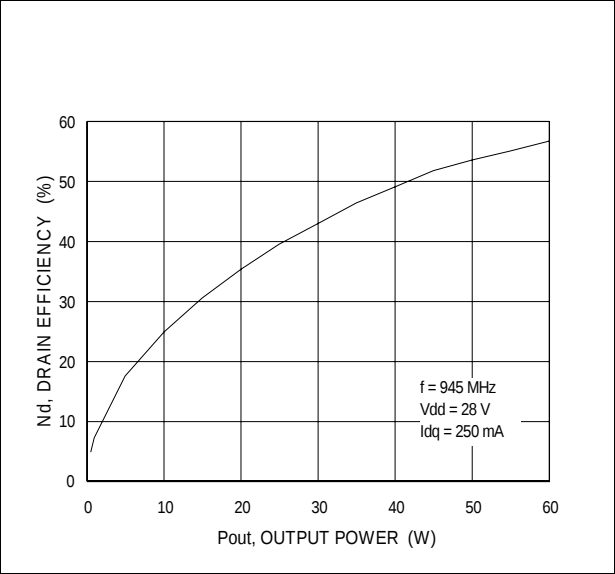


Figure 10. Output power vs bias current

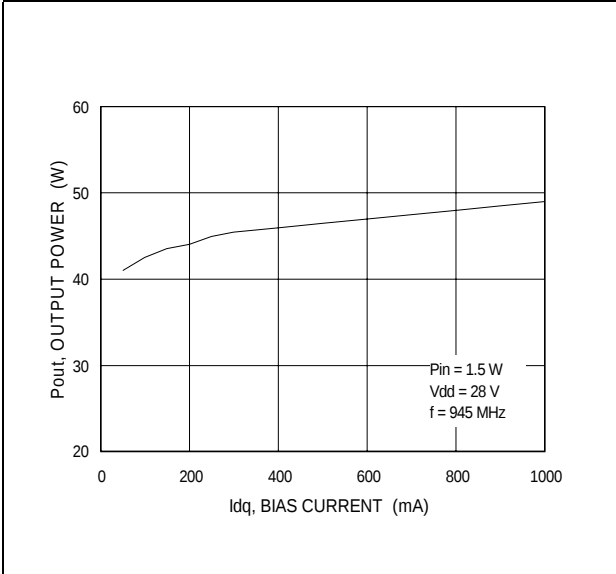


Figure 11. Drain efficiency vs bias current

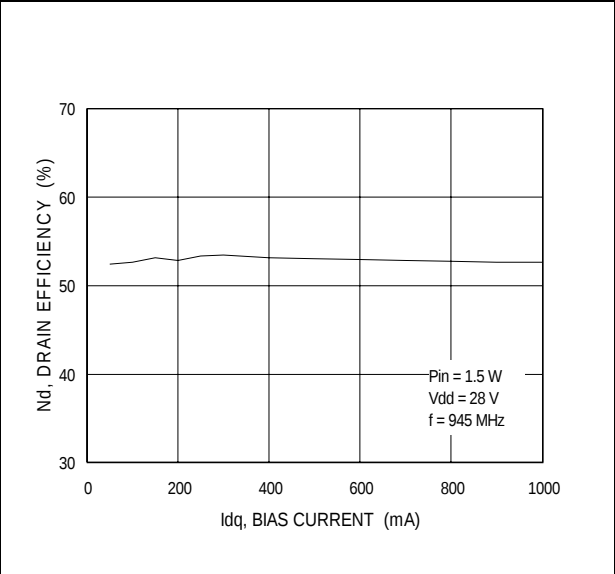


Figure 12. Output power vs drain voltage

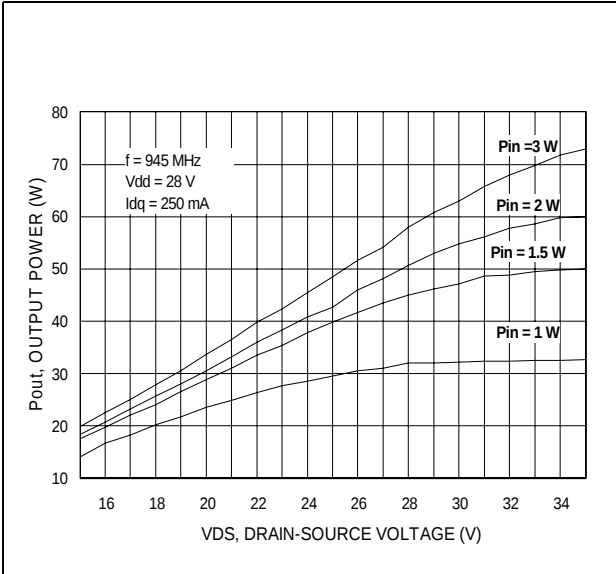
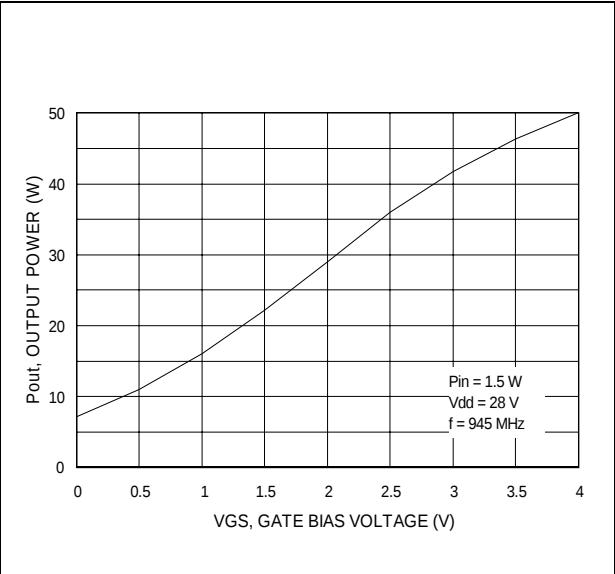
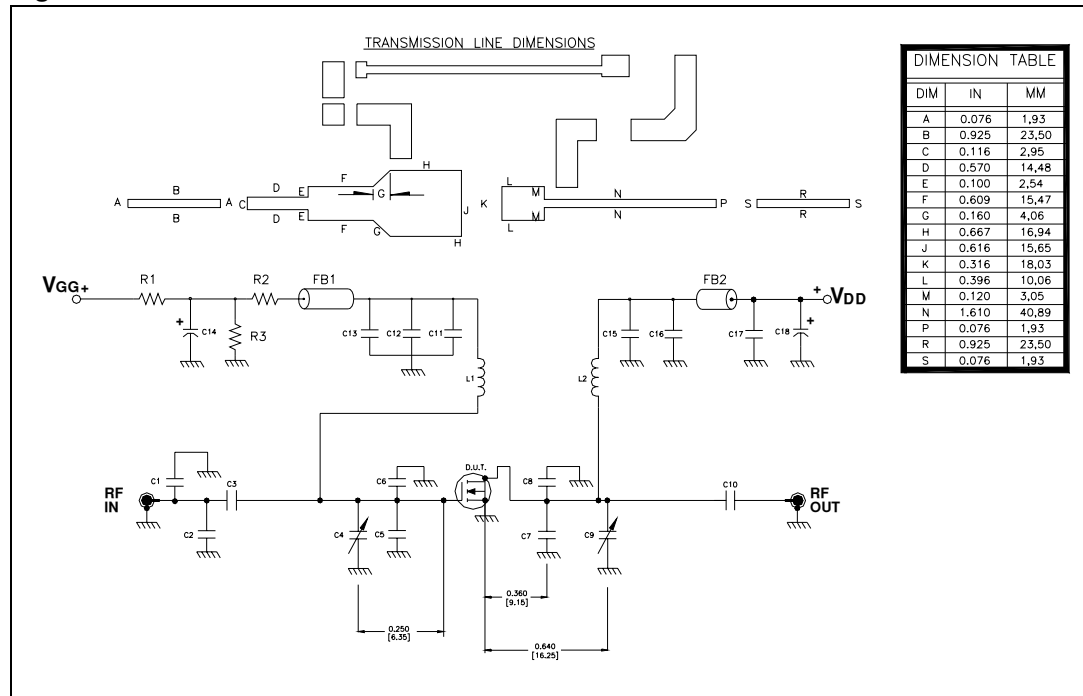


Figure 13. Output power vs gate bias voltage



5 Test circuit

Figure 14. Test circuit schematic



- Note:
- 1 Dimensions at component symbols are reference for component placement.
 - 2 Gap between ground & transmission line = 0.056 [1.42] +0.002 [0.05] -0.000 [0.00] typ.
 - 3 Dimensions of input and output component from edge of transmission lines.

Table 6. Test circuit component part list

Component	Description
L1,L2	INDUCTOR, 5 TURNS AIR WOUND #22AWG, ID 0.059{1.49}, NYLON COATED MAGNET WIRE
FB1,FB2	SHIELD BEAD SURFACE MOUNT EMI
R1	18 K OHM, 1 W SURFACE MOUNT CHIP RESISTOR
R2	4.7 M OHM, 1 W SURFACE MOUNT CHIP RESISTOR
R3	120 OHM, 2 W SURFACE MOUNT CHIP RESISTOR
C1,C2	3 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C3,C10,C11,C15	47 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C4,C9	0.8-8.0 pF GIGA TRIM VARIABLE CAPACITOR
C5,C6,C7,C8	7.5 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C12	1000 pF ATC 700B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C13,C17	0.1 μ F/500 V SURFACE MOUNT CERAMIC CHIP CAPACITOR
C14	10 μ F/50 V ALUMINUM ELECTROLYTIC RADIAL LEAD CAPACITOR
C16	100 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C18	220 μ F/63 V ALUMINUM ELECTROLYTIC RADIAL LEAD CAPACITOR
BOARD	ROGER, ULTRA LAM 2000, THK 0.030", $\epsilon_r = 2.55$ 2oz. ED cu 2 SIDES.

Figure 15. Test circuit

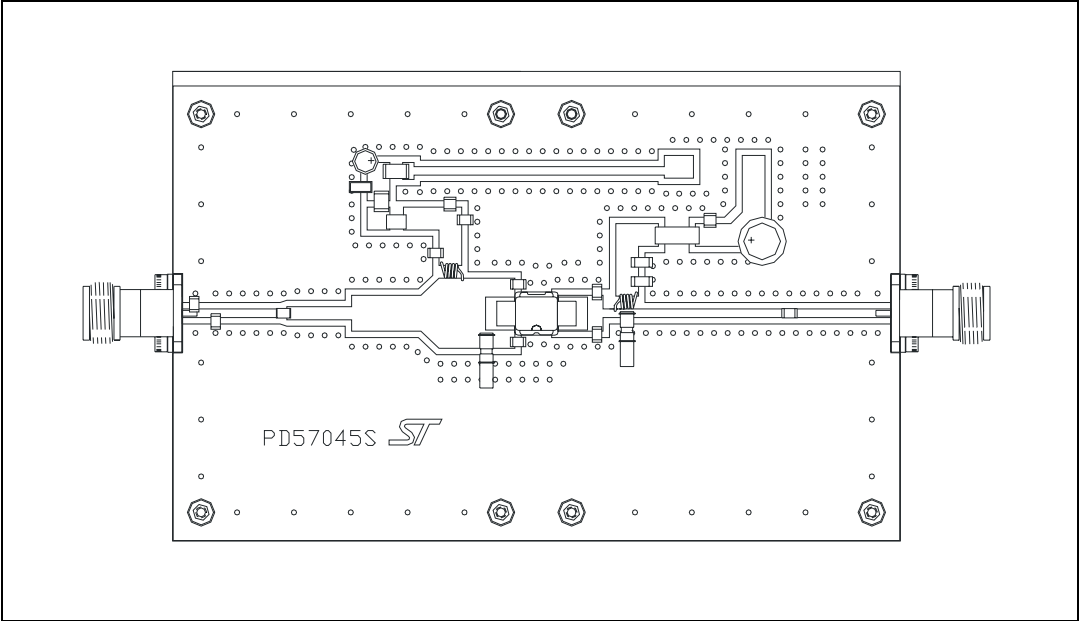
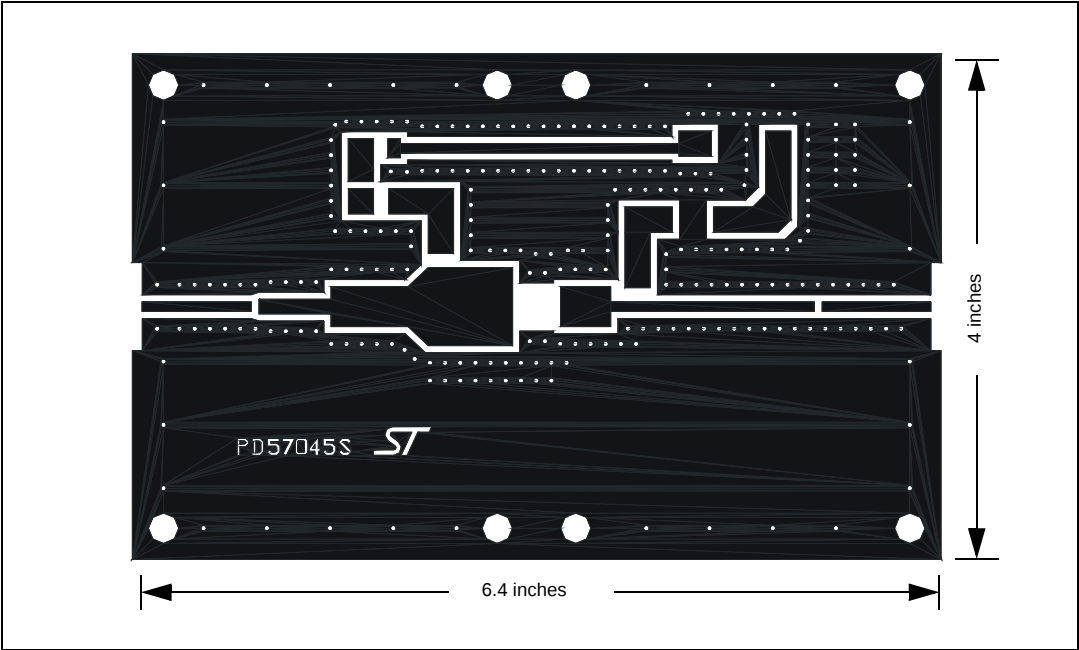


Figure 16. Test circuit photomaster



6 Common source s-parameter

6.1 PD57045S($V_{DS} = 13.5V$ $I_{DS} = 1.5A$)

Table 7. S-parameter

FREQ (MHz)	$ S_{11} $	$S_{11}\angle\Phi$	$ S_{21} $	$S_{21}\angle\Phi$	$ S_{12} $	$S_{12}\angle\Phi$	$ S_{22} $	$S_{22}\angle\Phi$
50	0.825	-170	14.34	85	0.014	-1	0.819	-171
100	0.875	-173	6.94	79	0.013	-6	0.824	-175
150	0.895	-175	4.67	75	0.013	-10	0.828	-175
200	0.908	-176	3.44	70	0.013	-14	0.837	-176
250	0.910	-177	2.70	65	0.012	-16	0.842	-176
300	0.916	-178	2.20	60	0.012	-18	0.854	-176
350	0.922	-178	1.82	55	0.011	-23	0.864	-176
400	0.926	-179	1.55	51	0.010	-25	0.874	-176
450	0.933	-179	1.32	47	0.010	-25	0.883	-177
500	0.937	-179	1.14	44	0.008	-25	0.893	-177
550	0.942	-180	1.00	40	0.008	-24	0.901	-177
600	0.946	180	0.88	37	0.007	-25	0.912	-177
650	0.949	180	0.79	34	0.007	-25	0.915	-178
700	0.951	179	0.70	32	0.006	-20	0.922	-178
750	0.954	179	0.63	29	0.005	-23	0.926	-179
800	0.958	178	0.57	27	0.005	-14	0.932	-179
850	0.961	178	0.52	24	0.004	-6	0.932	-180
900	0.963	178	0.47	22	0.004	3	0.942	179
950	0.964	177	0.44	20	0.004	1	0.942	180
1000	0.966	177	0.40	18	0.004	7	0.943	179
1050	0.967	176	0.37	16	0.003	26	0.946	179
1100	0.966	176	0.35	15	0.003	51	0.949	178
1150	0.969	176	0.32	13	0.003	56	0.950	179
1200	0.970	175	0.30	11	0.004	62	0.953	179
1250	0.970	175	0.29	9	0.004	55	0.967	178
1300	0.971	175	0.26	7	0.004	65	0.972	176
1350	0.972	174	0.25	6	0.004	71	0.958	176
1400	0.972	174	0.23	4	0.005	81	0.961	176
1450	0.970	174	0.22	3	0.006	91	0.958	175
1500	0.970	173	0.20	2	0.007	100	0.963	175

6.2 PD57045S ($V_{DS} = 28V$ $I_{DS} = 1.5A$)

Table 8. S-parameter

FREQ (MHz)	$ S_{11} $	$S_{11}\angle\Phi$	$ S_{21} $	$S_{21}\angle\Phi$	$ S_{12} $	$S_{12}\angle\Phi$	$ S_{22} $	$S_{22}\angle\Phi$
50	0.829	-161	20.72	92	0.012	2	0.718	-166
100	0.872	-168	10.33	82	0.011	-6	0.731	-170
150	0.897	-172	6.84	74	0.011	-10	0.745	-171
200	0.910	-174	5.02	68	0.010	-14	0.765	-171
250	0.913	-175	3.86	61	0.010	-17	0.783	-171
300	0.922	-176	3.10	55	0.009	-23	0.803	-171
350	0.928	-176	2.53	50	0.009	-25	0.823	-172
400	0.934	-177	2.12	45	0.008	-27	0.839	-172
450	0.941	-178	1.79	41	0.007	-26	0.856	-172
500	0.946	-178	1.53	37	0.006	-26	0.872	-173
550	0.949	-179	1.32	34	0.005	-27	0.884	-174
600	0.955	-179	1.16	31	0.005	-24	0.898	-174
650	0.959	-180	1.03	27	0.004	-18	0.902	-175
700	0.960	180	0.91	25	0.004	-17	0.914	-175
750	0.963	179	0.81	22	0.003	-7	0.919	-176
800	0.967	179	0.73	19	0.003	-1	0.928	-176
850	0.968	178	0.67	17	0.003	11	0.927	-177
900	0.968	178	0.60	15	0.003	28	0.937	-178
950	0.972	178	0.55	12	0.003	36	0.939	-178
1000	0.972	177	0.50	11	0.003	56	0.94	-179
1050	0.972	177	0.49	9	0.003	56	0.944	-179
1100	0.972	176	0.43	7	0.004	63	0.950	-180
1150	0.974	176	0.40	5	0.004	66	0.950	-179
1200	0.975	176	0.37	4	0.005	72	0.950	-180
1250	0.975	175	0.35	3	0.006	75	0.968	180
1300	0.976	175	0.32	0	0.006	77	0.973	178
1350	0.977	174	0.30	-1	0.006	81	0.960	178
1400	0.976	174	0.28	-2	0.006	84	0.960	177
1450	0.973	174	0.26	-3	0.007	98	0.958	177
1500	0.973	174	0.25	-4	0.008	102	0.963	176

7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

Table 9. PowerSO-10RF Formed lead (Gull Wing) Mechanical data

Dim.	mm.			Inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A1	0	0.05	0.1	0.	0.0019	0.0038
A2	3.4	3.5	3.6	0.134	0.137	0.142
A3	1.2	1.3	1.4	0.046	0.05	0.054
A4	0.15	0.2	0.25	0.005	0.007	0.009
a		0.2			0.007	
b	5.4	5.53	5.65	0.212	0.217	0.221
c	0.23	0.27	0.32	0.008	0.01	0.012
D	9.4	9.5	9.6	0.370	0.374	0.377
D1	7.4	7.5	7.6	0.290	0.295	0.298
E	13.85	14.1	14.35	0.544	0.555	0.565
E1	9.3	9.4	9.5	0.365	0.37	0.375
E2	7.3	7.4	7.5	0.286	0.292	0.294
E3	5.9	6.1	6.3	0.231	0.24	0.247
F		0.5			0.019	
G		1.2			0.047	
L	0.8	1	1.1	0.030	0.039	0.042
R1			0.25			0.01
R2		0.8			0.031	
T	2 deg	5 deg	8 deg	2 deg	5 deg	8 deg
T1		6 deg			6 deg	
T2		10 deg			10 deg	

Note: Resin protrusions not included (max value: 0.15 mm per side)

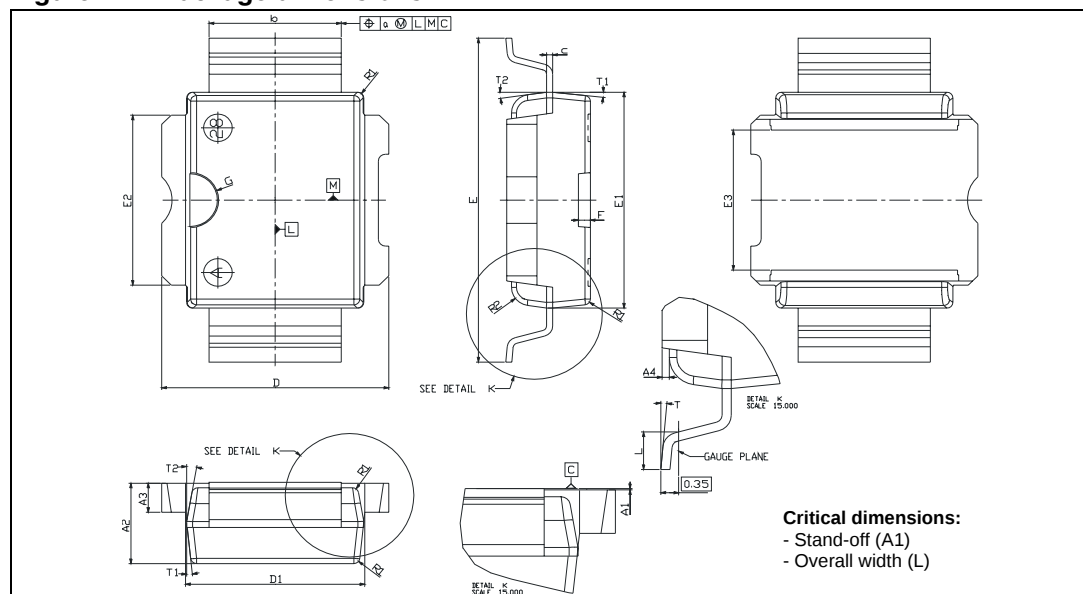
Figure 17. Package dimensions

Table 10. PowerSO-10RF Straight Lead Mechanical data

Dim.	mm.			Inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A1	1.62	1.67	1.72	0.064	0.065	0.068
A2	3.4	3.5	3.6	0.134	0.137	0.142
A3	1.2	1.3	1.4	0.046	0.05	0.054
A4	0.15	0.2	0.25	0.005	0.007	0.009
a		0.2			0.007	
b	5.4	5.53	5.65	0.212	0.217	0.221
c	0.23	0.27	0.32	0.008	0.01	0.012
D	9.4	9.5	9.6	0.370	0.374	0.377
D1	7.4	7.5	7.6	0.290	0.295	0.298
E	15.15	15.4	15.65	0.595	0.606	0.615
E1	9.3	9.4	9.5	0.365	0.37	0.375
E2	7.3	7.4	7.5	0.286	0.292	0.294
E3	5.9	6.1	6.3	0.231	0.24	0.247
F		0.5			0.019	
G		1.2			0.047	
R1			0.25			0.01
R2		0.8			0.031	
T1		6 deg			6 deg	
T2		10 deg			10 deg	

Note: Resin protrusions not included (max value: 0.15 mm per side)

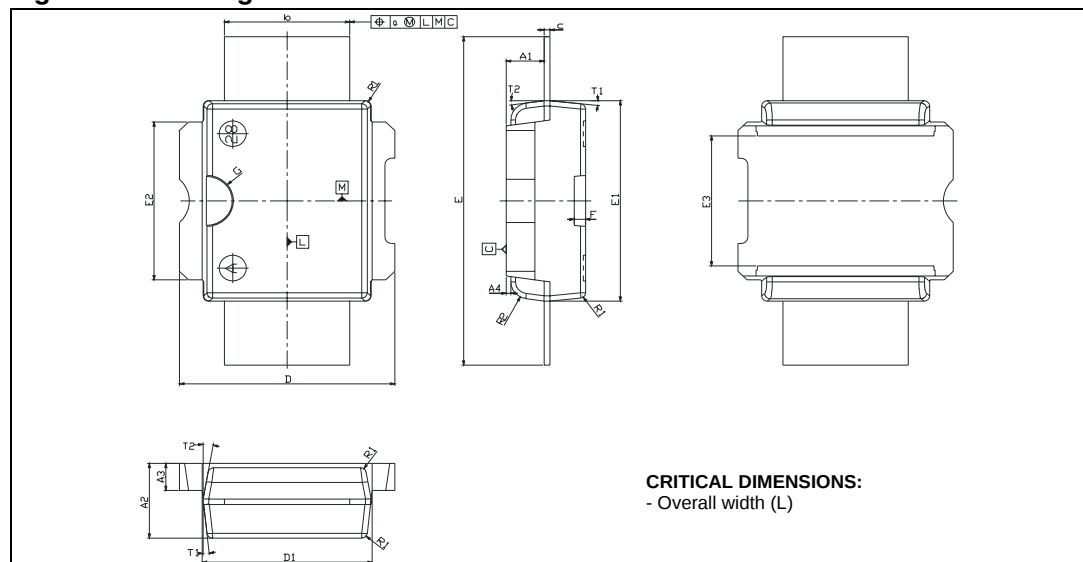
Figure 18. Package dimensions

Figure 19. Tube information

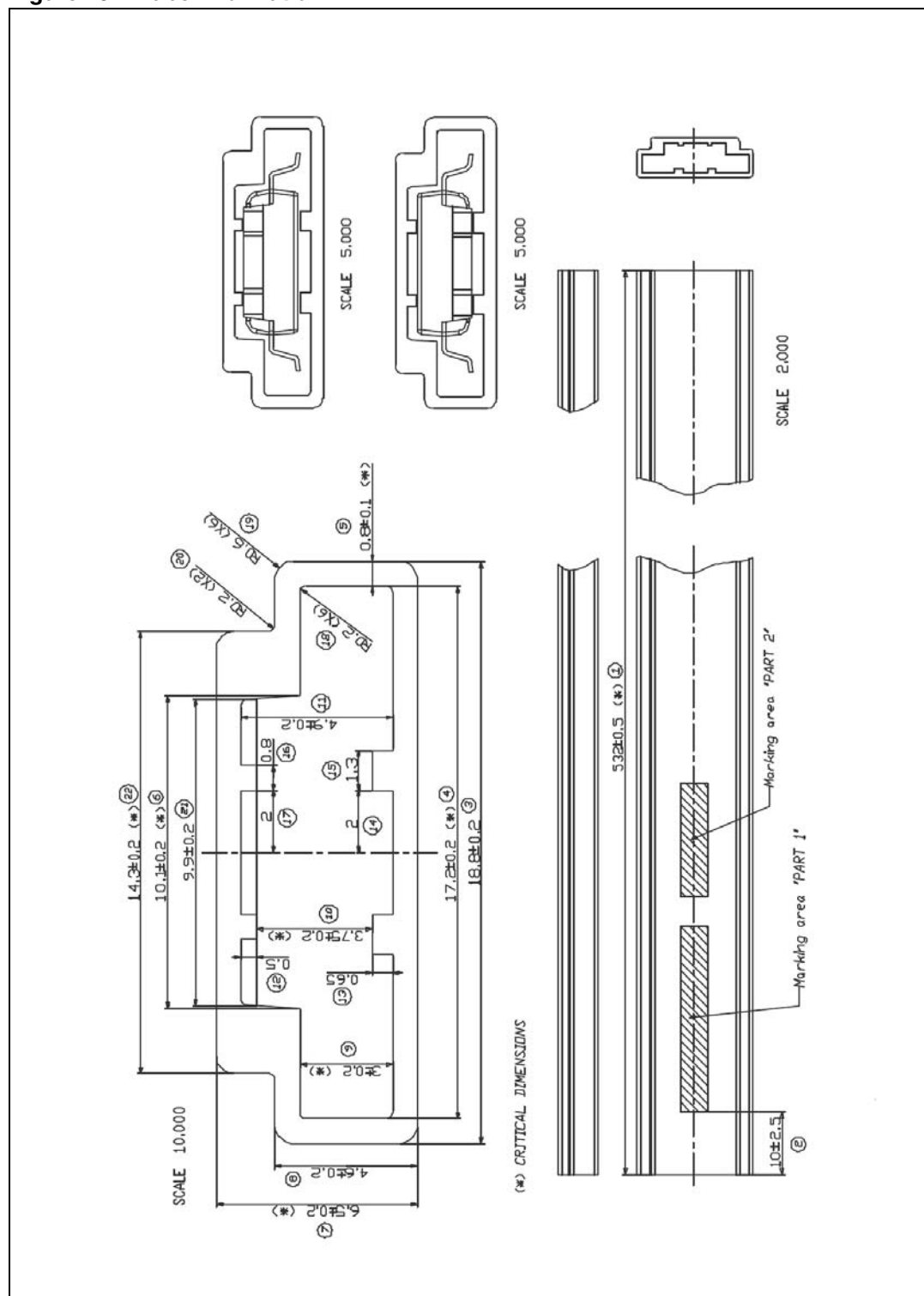
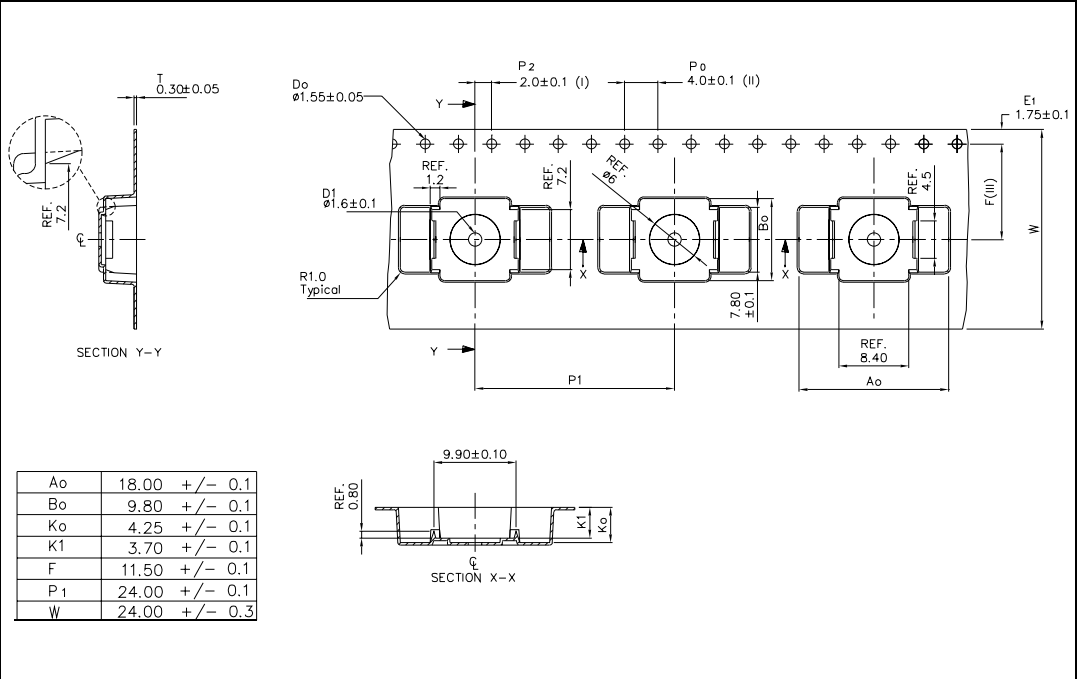


Figure 20. Reel information



8 Revision history

Table 11. Revision history

Date	Revision	Changes
08-Aug-2006	1	Initial release.

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